

**POLISHING LIQUID FOR POLISHING COMPOUND SEMICONDUCTOR
SUBSTRATE**

ABSTRACT

A polishing liquid for polishing a compound semiconductor substrate includes an aqueous solution in which a permanganate and a water-soluble compound of a weak acid and a Group III element, a lanthanoid, or a Group IV element are dissolved. Preferably, the pH of the polishing liquid is 3 to 7. In addition, preferably, the concentration of the permanganate is not less than 2.50 wt%, and the concentration of the water-soluble compound is 0.55 wt% to 5.50 wt%.

[FIG. 1]